

COMPLIANT

HALOGEN

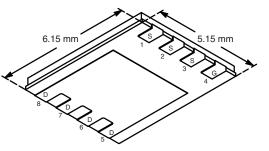
FREE

Available

Vishay Siliconix

N-Channel 60 V (D-S) Reduced Q_{gd}, Fast Switching MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)	
60	0.0078 at V _{GS} = 10 V	30	55	
	0.009 at V _{GS} = 6 V	30	55	



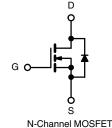
PowerPAK SO-8

FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Low Thermal Resistance PowerPAK[®] Package **RoHS**
- 100 % Rg and Avalanche Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Primary Side Switch
- Very Low R_g and $\mathsf{Q}_{gd},$ Critical for Minimizing Losses



Ordering Information: Si7138DP-T1-E3 (Lead (Pb)-free) Si7138DP-T1-GE3 (Lead (Pb)-free) and Halogen-free)

Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20		
	T _C = 25 °C		30		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C	I _D	30		
	T _A = 25 °C	U	19.7 ^{b, c}		
	T _A = 70 °C		15.7 ^{b, c}	A	
Pulsed Drain Current		I _{DM} 80			
Continuous Source-Drain Diode Current	T _C = 25 °C	I _S	30 ^a		
Continuous Source-Drain Diode Current	T _A = 25 °C	'S	4.5 ^{b, c}		
Avalanche Current	nt L = 0.1 mH		43		
Single-Pulse Avalanche Energy	L = 0.1 mm	E _{AS}	93	mJ	
	T _C = 25 °C		96		
Maximum Power Dissipation	T _C = 70 °C	P _D	61.5	w	
	T _A = 25 °C	١D	5.4 ^{b, c}		
	T _A = 70 °C		3.5 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg} - 55 to 150		<u></u>	
Soldering Recommendations (Peak Temperature) ^{d, e}			260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, f}	t ≤ 10 s	R _{thJA}	18	23	°C/W	
Maximum Junction-to-Case (Drain)	Steady State	R _{thJC}	1.0	1.5	C/W	

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

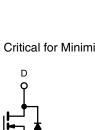
c. t = 10 s.

d. See solder profile (www.vishay.com/ppg?73461). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

f. Maximum under steady state conditions is 65 °C/W.

Document Number: 73530 S11-0212-Rev. C, 14-Feb-11



Bottom View

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	-						
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 V, I_{D} = 1 mA$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L = 250 µA		60.5		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	l _D = 250 μA		- 8.4			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4		
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zero Gate Voltage Drain Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
	IDSS	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΑ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	30			А	
Drain-Source On-State Resistance ^a		V _{GS} = 10 V, I _D = 19.7 A		0.0065	0.0078	Ω	
	R _{DS(on)}	V _{GS} = 6 V, I _D = 18 A		0.0073	0.009		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 19.7 A		84		S	
Dynamic ^b	<u> </u>			1	I		
Input Capacitance	C _{iss}			6900		pF	
Output Capacitance	C _{oss}	V _{DS} = 30 V, V _{GS} = 0 V, f = 1 MHz		470			
Reverse Transfer Capacitance	C _{rss}			200			
T + 1 0 + 01	Qg	V _{DS} = 30 V, V _{GS} = 10 V, I _D = 19.7 A		90	135	nC	
Total Gate Charge				55	83		
Gate-Source Charge	Q _{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 6 \text{ V}, I_{D} = 19.7 \text{ A}$		27.5			
Gate-Drain Charge	Q _{gd}			11			
Gate Resistance	R _g	f = 1 MHz		0.6	0.9	Ω	
Turn-On Delay Time	t _{d(on)}			47	70	-	
Rise Time	t _r	V_{DD} = 30 V, R_{L} = 3 Ω		120	180		
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{\text{GEN}} = 6 \text{ V}, \text{R}_{\text{g}} = 1 \Omega$		40	60		
Fall Time	t _f			8	15		
Turn-On Delay Time	t _{d(on)}			25	40	ns	
Rise Time	t _r	V_{DD} = 30 V, R_{I} = 3 Ω		12	20	-	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, \text{ R}_g = 1 \Omega$		50	75		
Fall Time	t _f			8	15		
Drain-Source Body Diode Characteris							
Continuous Source-Drain Diode Current	ا _S	T _C = 25 °C			30	٨	
Pulse Diode Forward Current ^a	I _{SM}				80	A	
Body Diode Voltage	V _{SD}	I _S = 2.7 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			45	70	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			80	120	nC	
Reverse Recovery Fall Time	t _a	$I_F = 10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{ T}_J = 25 \text{ °C}$		30			
Reverse Recovery Rise Time	t _b			15		ns	

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

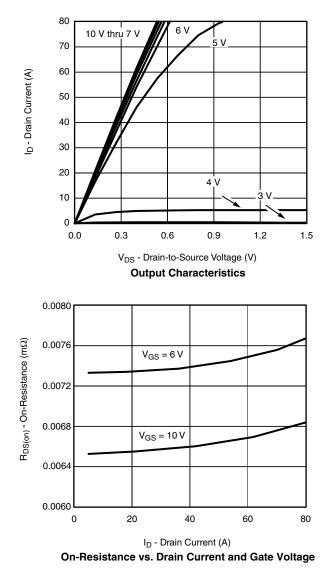
b. Guaranteed by design, not subject to production testing.

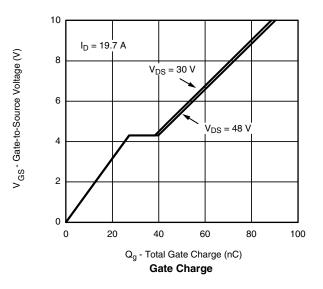
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

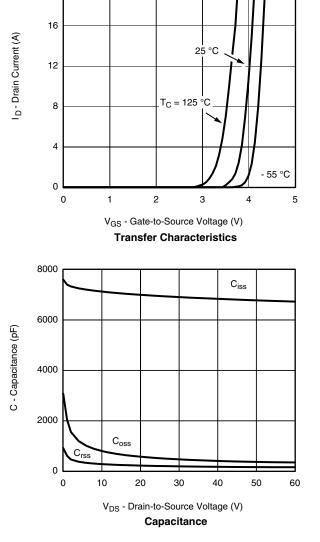


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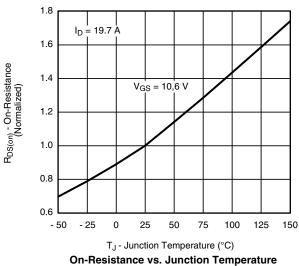
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







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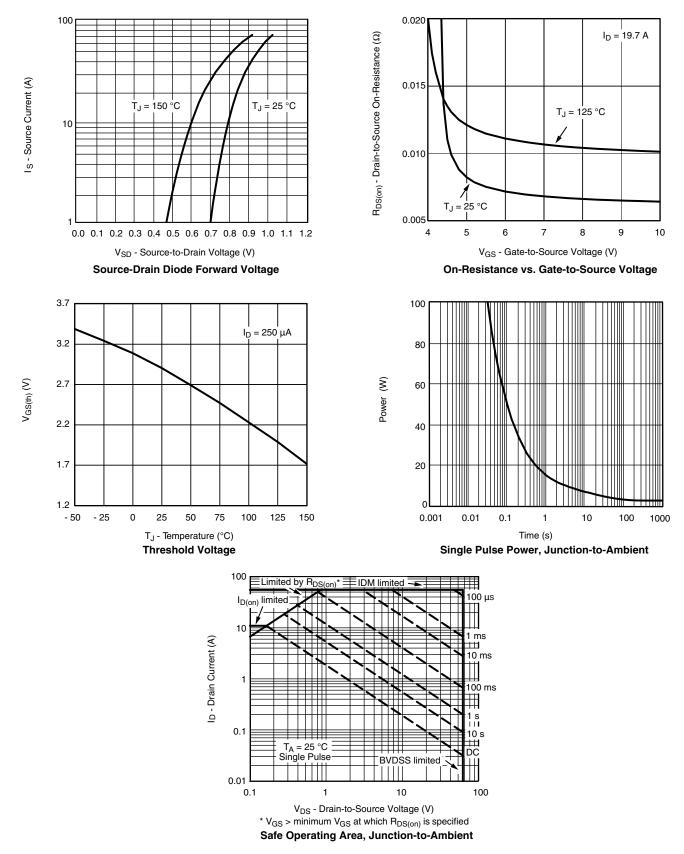


Document Number: 73530 S11-0212-Rev. C, 14-Feb-11

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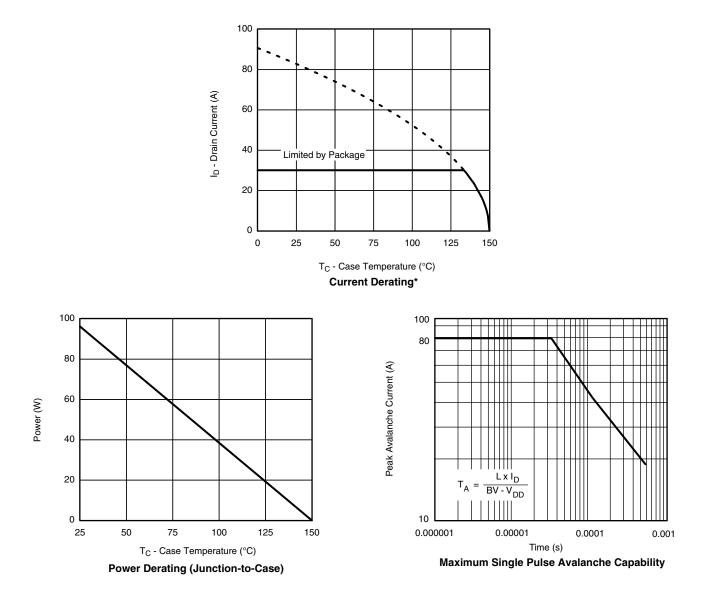
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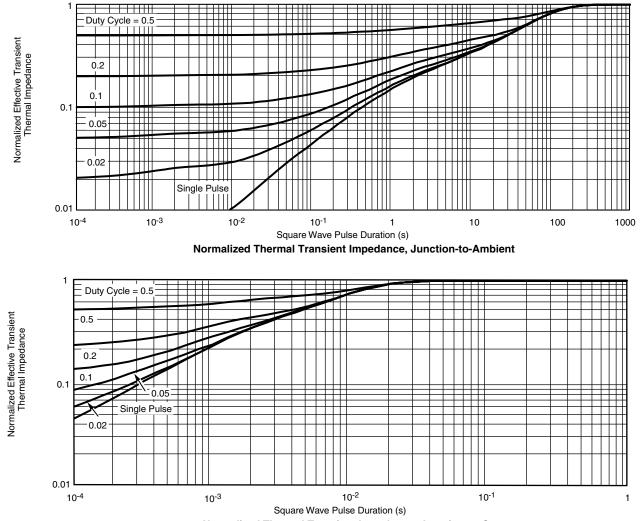


* The power dissipation P_D is based on $T_{J(max)} = 150 \text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?73530.

www.vishay.com 6



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